

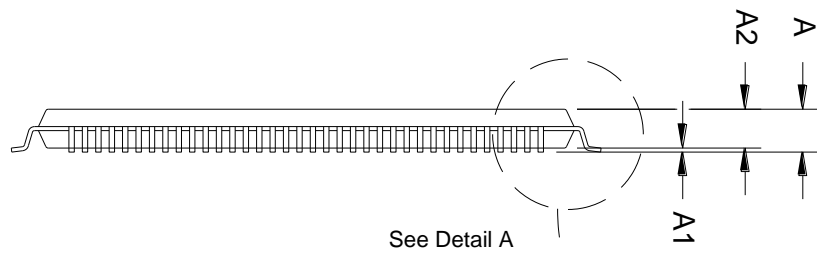
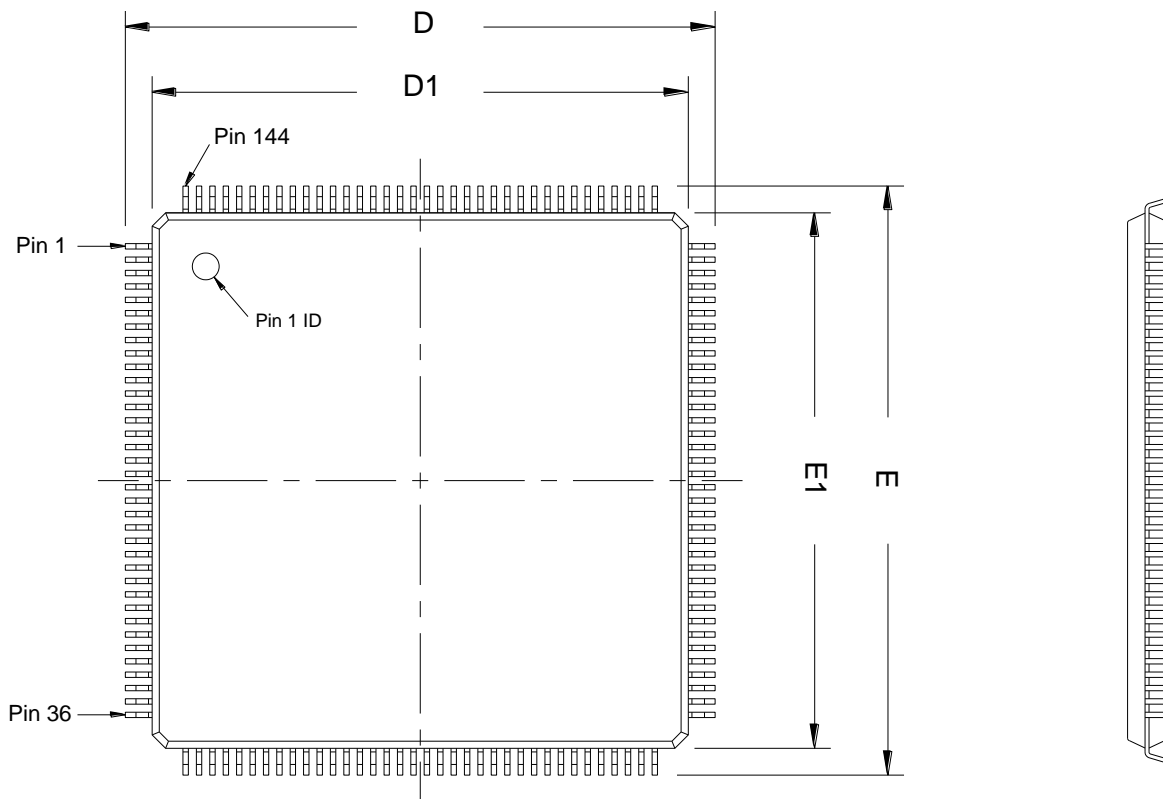
144-Pin Plastic Thin Quad Flat Pack (TQFP) - Wire Bond - A:1.60

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin 1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

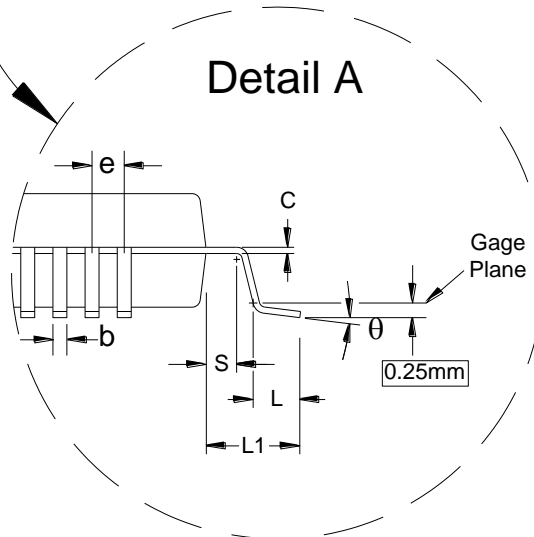
Package Information	
Description	Specification
Ordering Code Reference	T
Package Acronym	TQFP
Substrate Material	Copper
Lead Finish (plating)	Regular: 85Sn:15Pb (Typ.) Pb-free: Matte Sn
JEDEC Outline Reference	MS-029 Variation: BFB
Lead Coplanarity	0.003 inch (0.08 mm)
Weight	1.0 g (Typ.)
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table			
Symbol	Millimeters		
	Min.	Nom.	Max.
A	1.40	1.50	1.60
A1	0.05	0.10	0.15
A2	1.35	1.40	1.45
D	22.00 BSC		
D1	20.00 BSC		
E	22.00 BSC		
E1	20.00 BSC		
L	0.45	0.60	0.75
L1	1.00 REF		
S	0.20	-	-
b	0.17	0.22	0.27
c	0.09	-	0.20
e	0.50 BSC		
θ	0°	3.5°	7°

Package Outline



See Detail A



Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
July 2011	1.0	Initial release



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